

ABSTRACT

Disclosed in an embodiment of the present invention is an electroplating device, comprising an electroplating tank, a clamp, a positioning cylinder and an anode, wherein the positioning cylinder is located in the electroplating tank; the positioning cylinder is open at one end; the anode is located inside the positioning cylinder, and the positioning cylinder comes in contact with the anode in a sealing manner; and in the entire surface region of the anode, only a first surface comes in contact with an electroplating solution, and the first surface is parallel and opposite to a substrate, with the center of the first surface being aligned with the center of the substrate, and the size of the first surface being similar to that of an effective electroplating region of the substrate. By means of the electroplating device, an electric field generated by the anode is uniformly distributed on the surface of the substrate, thereby improving the uniformity of the electroplating height on the surface of the substrate. Further disclosed in an embodiment of the present invention is an electroplating method using the electroplating device.